

FIG. 1C

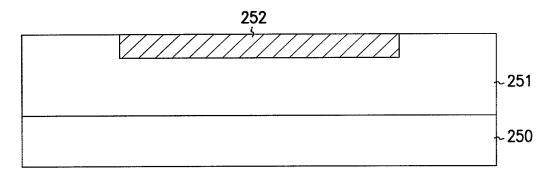


FIG. 2A

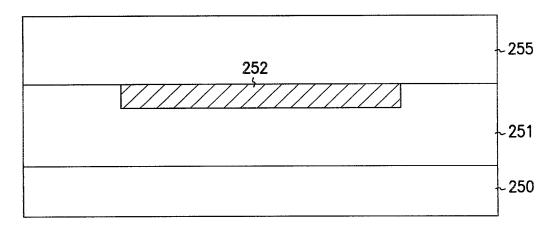


FIG. 2B

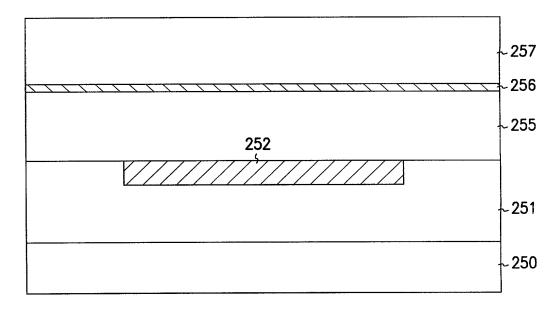


FIG. 2C

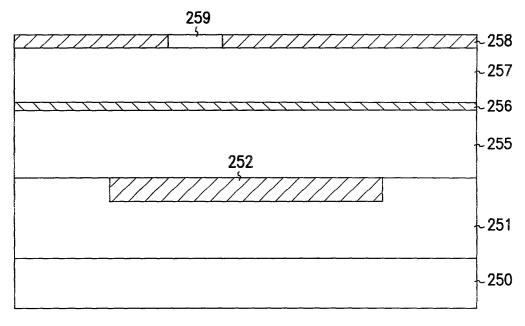


FIG. 2D

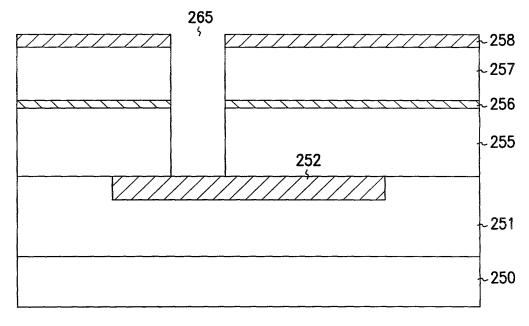


FIG. 2E

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of the last that the first the

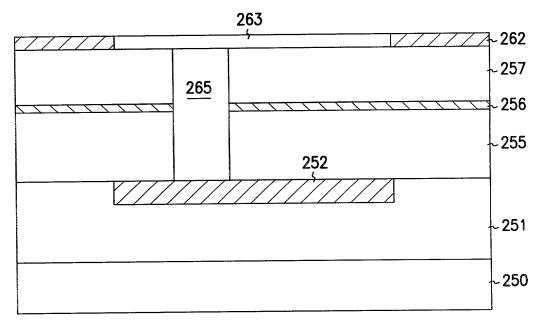


FIG. 2F

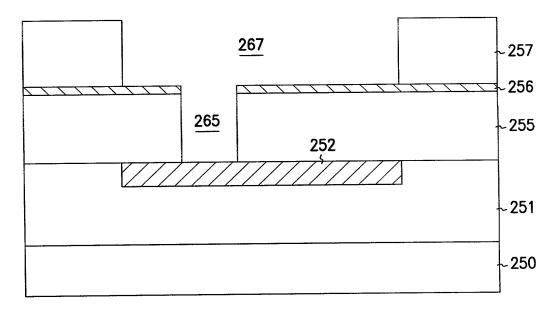


FIG. 2G

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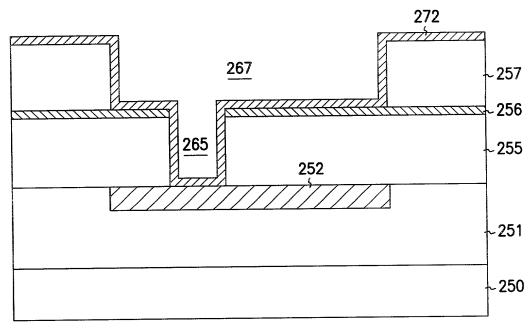


FIG. 2H

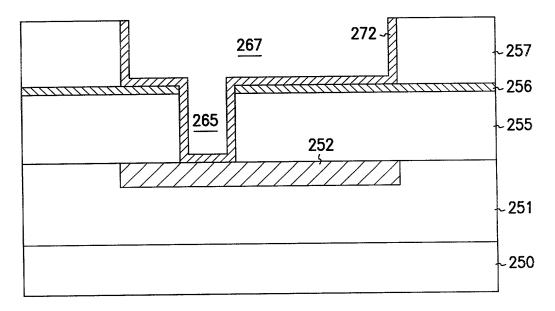
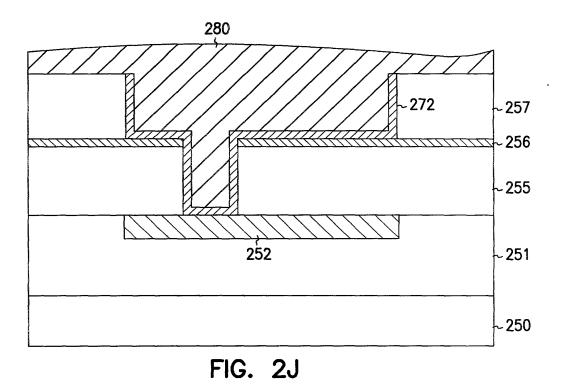
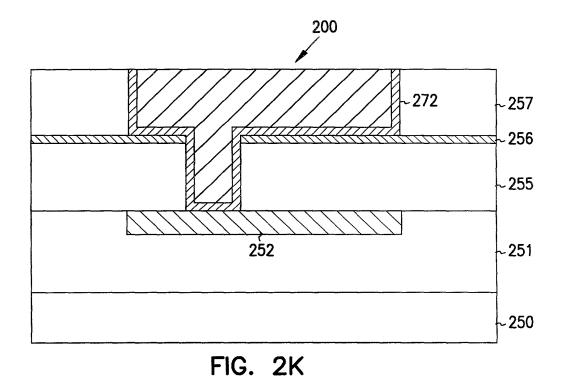
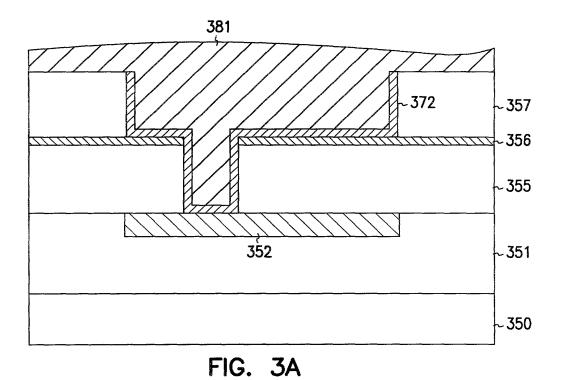


FIG. 21







300 -372 -356 -355 -351 -350

FIG. 3B

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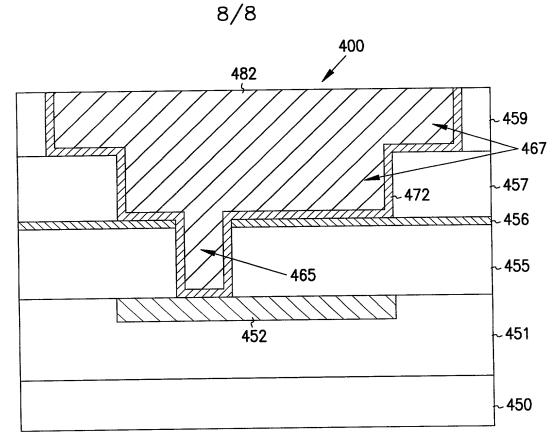


FIG. 4

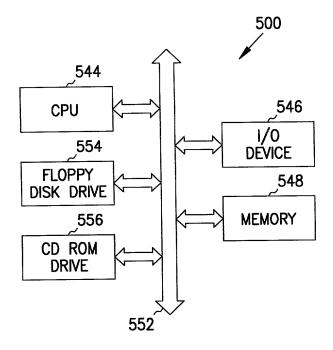


FIG. 5